MA2SD250G

Silicon epitaxial planar type

For super high speed switching

■ Features

• Forward current (Average) $I_{F(AV)} = 200 \text{ mA}$ rectification is possible

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	15	V
Repetitive peak reverse voltage	V _{RRM}	15	V
Forward current (Average)	I _{F(AV)}	200	mA
Peak forward current	I_{FM}	300	mA
Non-repetitive peak forward surge current *	I _{FSM}	1	A
Junction temperature	T_{j}	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

Package

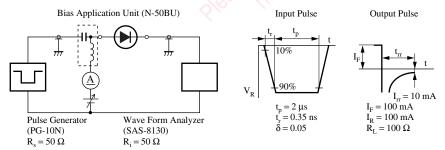
- Code SSMini2-F4
- Pin Name
 - 1: Anode
 - 2: Cathode
- Marking Symbol: 6L

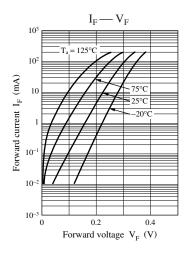
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

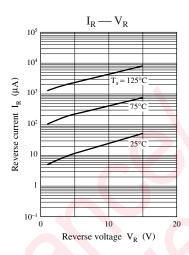
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _F	$I_F = 200 \text{ mA}$	VOD.	-0/10	0.39	V
Reverse current	I_R	$V_R = 6 \text{ V}$	2		50	μΑ
Terminal capacitance	C_{t}	$V_R = 1 \text{ V, f} = 1 \text{ MHz}$	03/	20		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$	0.7	3		ns
		$I_{rr} = 10 \text{ mA}, R_{L} = 100 \Omega$				

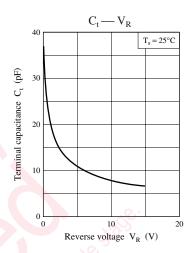
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

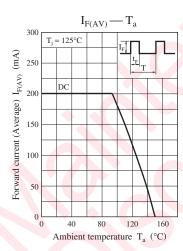
- This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 250 MHz.
- 4. *: t_{rr} measurement circuit





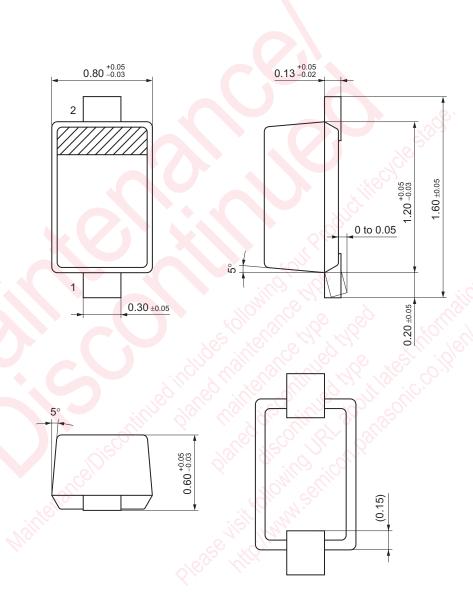






2 SKH00179AED

SSMini2-F4 Unit: mm



SKH00179AED 3

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